

The specification incorporates by reference the disclosure of German priority document 199 27 516.5 filed 16 June 1999 and PCT/EP00/05442 filed 14 June 2000.

The present invention is, of course, in no way restricted to the specific disclosure of the specification and drawings, but also encompasses any modifications within the scope of the appended claims.--

IN THE CLAIMS:

Please cancel claims 1 - 31, and replace them with the attached claims 32-~~62~~.

IN THE DRAWINGS:

Please replace page 4 of the drawings (Figs. 4a, 4b, and 4c) with the attached drawing proposal (also page 4, Figs. 4a, 4b, and 4c).

REMARKS

Claims 32 - 62 are pending in the application.

Appropriate headings have been added to the specification, and claims from the literal translation have been replaced by claims drafted in conformity with U.S. Patent practice.

The application in its amended state is believed to be in condition for allowance. However, should the Examiner have any comments or suggestions, or wish to discuss the merits of the application, the undersigned would very much welcome a telephone call in order to expedite placement of the application into condition for allowance.

Respectfully submitted,

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32. A method of producing a data carrier by adhering at least two substrates to one another, said method including the steps of:

providing a first substrate;

pressing an adhesive film, which is adhesive on two sides,

5 against said first substrate via a rotating pressure roller while moving said first substrate and said pressure roller relative to one another, wherein such relative movement extends parallel to a surface of said first substrate;

aligning a second substrate relative to said first substrate; and

10 joining said first and second substrates together.

33. A method according to claim 32, which includes the step of withdrawing said adhesive film from a carrier film during or after application of said adhesive film against said first substrate.

15 34. A method according to claim 32, which includes the step of withdrawing a protective film from said adhesive film prior to application of said adhesive film against said first substrate.

35. A method according to claim 33, wherein a shape and size of said adhesive film corresponds to surfaces of said first and second substrates that are to be adhesively joined.

20 36. A method according to claim 35, wherein sections of said adhesive film that correspond to a shape and size of said first and second substrate are punched onto said carrier film.

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37. A method according to claim 32, which includes the step of applying said adhesive film in a centered manner to a surface of said first substrate that is to be adhered.

5 38. A method according to claim 32, which includes the step of aligning said adhesive film and said first substrate with one another prior to said step of pressing said adhesive film against said first substrate.

39. A method according to claim 32, which includes the step of controlling a pressure of said pressure roller.

10 40. A method according to claim 32, which includes the step of holding said adhesive film at a pre-specified angle relative to a surface of said first substrate prior to said step of pressing said adhesive film against said first substrate.

15 41. A method according to claim 32, which includes the step of moving said first substrate linearly past said pressure roller.

42. A method according to claim 32, which includes the step of rotating said pressure roller synchronously to a movement of said first substrate.

20 43. A method according to claim 32, wherein said first and second substrates are placed on a centering and holding device for aligning said substrate.

44. A method according to claim 43, wherein prior to said joining step, said centering and holding device holds said first and second substrate spaced from one another.

a 2 45. A method according to claim 32, wherein said step of joining said first and second substrates together is effected in a vacuum.

46. A method according to claim 32, wherein said joining step
5 includes pressing said first and second substrates together.

47. A method according to claim 46, which includes the step of controlling a pressure exerted upon said first and second substrates.

48. A method according to claim 32, wherein said adhesive film is an adhesive film that responds to pressure.

10 49. A method according to claim 32, wherein said adhesive
film is hardened.

50. A method according to claim 32, wherein said adhesive film is a single layer of adhesive material.

51. An apparatus for producing a data carrier having at least two substrates that are adhered to one another, comprising:

a laminating station for applying to a first substrate an adhesive film that is adhesive on two sides, wherein said laminating station comprises a rotatable pressure roller and a device for effecting relative movement between said first substrate and said pressure roller, wherein such relative movement extends parallel to a surface of said first substrate; and

a substrate adhering station for aligning and joining said first substrate and a second substrate together.

52. An apparatus according to claim 51, wherein a shape and size of said adhesive film corresponds to surfaces of said first and second substrates to be adhered.

53. An apparatus according to claim 51, wherein sections of said adhesive film that correspond to a shape and size of surfaces of said first and second substrates to be adhered are punched onto a carrier film.

10 54. An apparatus according to claim 51, wherein said laminating station is provided with an aligning unit for aligning said adhesive film with a surface of said substrate that is to be adhered.

55. An apparatus according to claim 54, wherein said aligning unit is provided with at least one linear movement unit for said substrate.

15 56. An apparatus according to claim 51, wherein a centering and holding device is provided that in a first position holds said first and second substrates spaced apart and in a second position enables a centered joining of said first and second substrates.

57. An apparatus according to claim 51, wherein said substrate adhering station is provided with a vacuum chamber.

20 58. An apparatus according to claim 57, wherein said vacuum chamber is provided with a hood and a base that is formed by a substrate support element.

59. An apparatus according to claim 56, wherein said substrate adhering station is provided with a pressure ram.

60. An apparatus according to claim 59, wherein said pressure ram is provided with an element for actuating said centering and holding device between said first and second positions.

61. An apparatus according to claim 51, wherein said substrate adhering station is provided with an apparatus for applying compressed air to at least one of said first and second substrates for pressing said substrates together.

62. An apparatus according to claim 51, wherein said adhesive film is a layer of adhesive material.